



ALLIANCE MEMORY MDS REPORT

Part Number:		AS4C128M16D2-25BCN / AS4C128M16D2-25BIN							
Wiegth (mg):		262.74 mg							
No.	Part Name	Material Name	Material mass (mg)	Substance in Materials	CAS Number	Element wt (%)	Element wt (mg)	wt % of total unit wt	PPM
1	Substrate	Core-HL-832	47.635	Core-HL-832	Trade secret	60.893%	29.01	11.04%	608929
				Solder Mask-AUS308	Trade secret	13.910%	6.63	2.52%	139095
				Cu	7440-50-8	24.358%	11.60	4.42%	243580
				Ni	7440-02-0	0.758%	0.36	0.14%	7576
				Au	7440-57-5	0.082%	0.04	0.01%	820
2	Die Adhesive (down)	EM700	2.239	Phenol resin	28453-20-5	15.000%	0.34	0.1278%	150000
				Silicon dioxide (SiO2)	60676-86-0	30.000%	0.67	0.2557%	300000
				Synthetic Rubber	Trade secret	40.000%	0.90	0.3409%	400000
				Epoxy Resin	9003-36-5	15.000%	0.34	0.1278%	150000
3	Die Adhesive (up)	EM310	2.239	Phenol resin	28453-20-5	15.000%	0.34	0.13%	150000
				Silicon dioxide (SiO2)	60676-86-0	40.000%	0.90	0.34%	400000
				Synthetic Rubber	Trade secret	15.000%	0.34	0.13%	150000
				Epoxy Resin	9003-36-5	30.000%	0.67	0.26%	300000
4	Gold Wire	Au	0.822	Gold	7440-57-5	100.000%	0.82	0.31%	1000000
5	Compound	9740Z	121.035	Epoxy resin1	Trade secret	4.000%	4.84	1.84%	40000
				Epoxy resin2	Trade secret	3.000%	3.63	1.38%	30000
				Hardener	Trade secret	4.500%	5.45	2.07%	45000
				Carbon black	1333-86-4	0.300%	0.36	0.14%	3000
				Silica	60676-86-0	88.200%	106.75	40.63%	882000
6	Solder Ball	M705	29.658	Sn	7440-31-5	96.529%	28.63	12.41%	965287
				Ag	7440-22-4	3.034%	0.90	0.39%	30335
				Cu	7440-50-8	0.438%	0.13	0.06%	4378
7	Chip	Silicon	59.112	Silica	7440-21-3	100.000%	59.11	22.50%	1000000